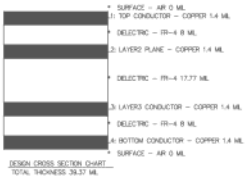


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-8.0	PLATED	151
*	12.0	+3.0/-12.0	PLATED	9
*	20.0	+3.0/-3.0	PLATED	29



FABRICATION NOTES

1. BASE MATERIAL

A. 1 MM +/- 10% THICK GLASS EPOXY, FR-4, TG 170

NATURAL COLOR NEMA GRADE

B. COPPER WEIGHT AS PER PROVIDED STACK-UP

2. FINISH: ENIG. NO EXPOSED COPPER PERMITTED

3. ALL TRACE WIDTHS ARE STATED AS FINISHED TRACE WIDTHS

4. DRILL SIZES ARE STATED AS TOOL SIZES

5. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE STATED

6. SOLDERMASK

A. PHOTO-MADED LIQUID POLYMER IN ACCORDANCE WITH IPC-3500, TYPE B, CLASS 1, OVER BARE COPPER AS INDICATED WITHIN THE ELECTRONIC DATA

B. SOLDERMASK COLOR IS TO BE GREEN

C. FINISH IS TO BE MATTE

7. SIKSCREEN

A. SIKSCREEN AS INDICATED WITHIN THE ELECTRONIC DATA

B. SIKSCREEN TO BE REMOVED FROM WAS, PADS, AND HOLES PROVIDING A MINIMUM CLEARANCE OF .005 INCHES

C. VENDORS UL LOGO OR DESIGNATION SHALL BE RUBBER STAMPED OR SIKSCREENED AT THE VENDORS DISCRETION ON EITHER SIDE OF THE BOARD

8. OTHER APPLICABLE STANDARDS

A. FABRICATE PER IPC-2221A CLASS 2 LEVEL B

B. FABRICATE PER IPC-2221A CLASS 2 LEVEL B

C. FABRICATE PER IPC-2221A CLASS 2 LEVEL B

D. FABRICATE PER IPC-2221A CLASS 2 LEVEL B

E. THIS BOARD SHALL CONFORM TO UL94V-0

9. OTHER APPLICABLE NOTES

A. REFER TO STACK-UP AND IMPEDANCE INFORMATION

B. SOLDERMASK IS ACCEPTABLE ON INNER SIGNAL LAYERS

C. COPPER THICKNESS MAY NOT BE ADDED TO SIGNAL DESIGN, ONLY TO PANEL

D. BOARD SHALL BE 100% DIELECTRICALLY TESTED FOR OPEN AND SHORTS. THE RESULTS OF THE TEST SHALL BE DOCUMENTED AND DELIVERED WITH EACH LOT

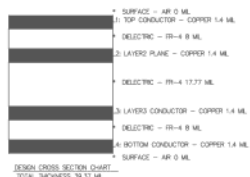
E. ALL MATERIALS USED WITHIN THE FABRICATION ARE TO BE ROHS COMPLIANT, AND MUST SUPPORT A PB-FREE ASSEMBLY PROCESS (E.G. ACCEPTABLE TQ/D, ETC)

F. BOARD DESIGN: PCBs SHALL BE ROUTED WITH MOUSE BITES, NO V-SCORE ON ANY SIDE, INCLUDE TOLLING HOLES AND TOLLING. BOARDS TO REMAIN ON THE PANEL FOR ASSEMBLY

12. TARGET IMPEDANCE LAYER 1: 0.01409 INCH TRACK WIDTH = 50 OHM +/- 10%

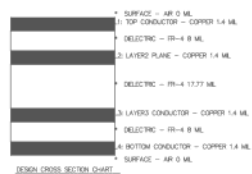
13. ANY ARTWORK MODIFICATIONS MUST BE REVIEWED AND APPROVED BY MMB NETWORKS PRIOR TO MANUFACTURING

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-8.0	PLATED	151
*	12.0	+3.0/-12.0	PLATED	9
*	20.0	+3.0/-3.0	PLATED	29



- FABRICATION NOTES
1. BASE MATERIAL
 - A. 1 MM +/- 10% THICK GLASS EPOXY, FR-4, TG 170
 - NATURAL COLOR NEMA GRADE
 2. COPPER WEIGHT AS PER PROVIDED STACK-UP
 3. FINISH: ENG. NO EXPOSED COPPER PERMITTED
 4. ALL TRACE WIDTHS ARE STATED AS FINISHED TRACE WIDTHS
 5. DRILL SIZES ARE STATED AS TOOL SIZES
 6. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE STATED
 7. SOLDERMASK
 - A. PHOTO-MADED LIQUID POLYMER IN ACCORDANCE WITH IPC-SUBM400, TYPE B1, CLASS 1 OVER BARE COPPER AS INDICATED WITHIN THE ELECTRONIC DATA
 - B. SOLDERMASK COLOR IS TO BE GREEN
 - C. FINISH IS TO BE MATTE
 8. SILKSREEN
 - A. SILKSREEN AS INDICATED WITHIN THE ELECTRONIC DATA USING NON CONDUCTIVE WHITE EPOXY INK
 - B. SILKSREEN TO BE REMOVED FROM VAS, PADS, AND HOLES PROVIDING A MINIMUM CLEARANCE OF 0.005 INCHES
 - C. ANY OTHERS, UL LOGO OR DESIGNATION SHALL BE RUBBER STAMPED OR SILKSREENED BY THE VENDORS DISCRETION ON OTHER SIDE OF THE BOARD
 - D. OTHER APPLICABLE STANDARDS
 - E. FABRICATE PER IPC-2221 CLASS 2 LEVEL B
 - F. IPC-2222 TYPE 1, ASSET 1 & 2, IPC-A-6000 CLASS 2
 - G. FABRICATE IN ACCORDANCE WITH IPC-6012B CLASS 2, PER IPC-6011 USING SUPPLIED DATA FILES
 - H. THE BOARD SHALL CONFORM TO UL94V-0
 9. OTHER APPLICABLE NOTES
 - A. REFER TO STACK-UP AND IMPEDANCE INFORMATION
 - B. TEARDROPPING IS ACCEPTABLE ON INNER SIGNAL LAYERS
 - C. CORNER THEVING MAY NOT BE ADDED TO PCB DESIGN, ONLY TO PANEL
 - D. BOW OR TWIST NOT TO EXCEED 0.178 MM/250.8 MM
 - E. THE PCB SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. THE RESULTS OF THIS TEST SHALL BE DOCUMENTED AND DELIVERED WITH EACH LOT
 - F. DIMENSIONAL COMPLIANCE IS REQUIRED
 - G. ALL MATERIALS USED WITHIN THE FABRICATION ARE TO BE ROHS COMPLIANT AND MUST SUPPORT A PB-FREE ASSEMBLY PROCESS (E.G. ACCEPTABLE TIG WELD, ETC)
 - H. PANEL DESIGN: PCBs SHALL BE ROUTED WITH MOUSE BITES, NO V-Score ON ANY SIDE
 - I. INCLUDE TOOLING HOLES AND LOCATIONALS. BOARDS TO REMAIN ON THE PANEL FOR ASSEMBLY.
 - J. TARGET IMPEDANCE LAYER 1: 0.01409 INCH TRACK WIDTH = 50 OHM +/- 10%
 - K. ANY ARTWORK MODIFICATIONS MUST BE REVIEWED AND APPROVED BY MMB NETWORKS PRIOR TO MANUFACTURING

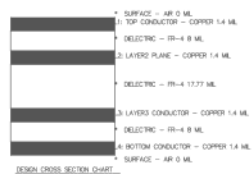
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-8.0	PLATED	151
*	12.0	+3.0/-12.0	PLATED	9
*	20.0	+3.0/-3.0	PLATED	29



FABRICATION NOTES

1. BASE MATERIAL
 - A. 1 MM +/- 10% THICK GLASS EPOXY, FR-4, TG 170
 - NATURAL COLOR NEMA GRADE
2. FINISH: ENG. NO EXPOSED COPPER PERMITTED
3. ALL TRACE WIDTHS ARE STATED AS FINISHED TRACE WIDTHS
4. DRILL SIZES ARE STATED AS TOOL SIZES
5. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE STATED
6. SOLDERMASK
 - A. PHOTO-MADED LIQUID POLYMER IN ACCORDANCE WITH IPC-SUBM400, TYPE B1, CLASS 1 OVER BARE COPPER AS INDICATED WITHIN THE ELECTRONIC DATA
 - B. SOLDERMASK COLOR IS TO BE GREEN
 - C. FINISH IS TO BE MATTE
7. SILKSREEN
 - A. SILKSREEN AS INDICATED WITHIN THE ELECTRONIC DATA USING NON CONDUCTIVE WHITE EPOXY INK
 - B. SILKSREEN TO BE REMOVED FROM VAS, PADS, AND HOLES PROVIDING A MINIMUM CLEARANCE OF 0.005 INCHES
 - C. ANY OTHERS, UL LOGO OR DESIGNATION SHALL BE RUBBER STAMPED OR SILKSREENED BY THE VENDORS DISCRETION ON OTHER SIDE OF THE BOARD
 - D. OTHER APPLICABLE NOTES
8. FABRICATE PER IPC-2221, CLASS 2 LEVEL B
 - IPC-2222, TYPE 1, ASSET 1 & 2, IPC-A-6000, CLASS 2
 - IPC-2223, TYPE 1, ASSET 1 & 2, IPC-A-6000, CLASS 2
 - PER IPC-6011 USING SUPPLIED DATA FILES
 - C. THIS BOARD SHALL CONFORM TO UL94V-0
9. OTHER APPLICABLE NOTES
 - A. REFER TO STACK-UP AND IMPEDANCE INFORMATION
 - B. TEARDROPPING IS ACCEPTABLE ON INNER SIGNAL LAYERS
 - C. COPPER THICKNESS MAY NOT BE ADDED TO PCB DESIGN, ONLY TO PANEL
 - D. BOW OR WARP NOT TO EXCEED 0.178 MM (7.0 MIL)
 - E. THE PCB SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. THE RESULTS OF THIS TEST SHALL BE DOCUMENTED AND DELIVERED WITH EACH LOT
 - F. UNITS COMPLIANCE IS REQUIRED
 - G. ALL MATERIALS USED WITHIN THE FABRICATION ARE TO BE ROHS COMPLIANT AND MUST SUPPORT A PB-FREE ASSEMBLY PROCESS (E.G. ACCEPTABLE TIG WELD, ETC)
 - H. PANEL DESIGN: PCBs SHALL BE ROUTED WITH MOUSE BITES, NO V-SCORE ON ANY SIDE
 - I. INCLUDE TOOLING HOLES AND LOCATIONALS. BOARDS TO REMAIN ON THE PANEL FOR ASSEMBLY.
 - J. TARGET IMPEDANCE LAYER 1: 0.01409 INCH TRACK WIDTH = 50 OHM +/- 10%
 - K. ANY ARTWORK MODIFICATIONS MUST BE REVIEWED AND APPROVED BY MMB NETWORKS PRIOR TO MANUFACTURING

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-8.0	PLATED	151
*	12.0	+3.0/-12.0	PLATED	9
*	20.0	+3.0/-3.0	PLATED	29



FABRICATION NOTES

1. BASE MATERIAL
 - A. 1 MM +/- 10% THICK GLASS EPOXY, FR-4, TG 170
 - NATURAL COLOR NEMA GRADE
2. COPPER WEIGHT AS PER PROVIDED STACK-UP
3. FINISH: ENG. NO EXPOSED COPPER PERMITTED
4. ALL TRACE WIDTHS ARE STATED AS FINISHED TRACE WIDTHS
5. DRILL SIZES ARE STATED AS TOOL SIZES
6. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE STATED
7. SOLDERMASK
 - A. PHOTO-MADED LIQUID POLYMER IN ACCORDANCE WITH IPC-SUBM400, TYPE B1, CLASS 1 OVER BARE COPPER AS INDICATED WITHIN THE ELECTRONIC DATA
 - B. SOLDERMASK COLOR IS TO BE GREEN
 - C. FINISH IS TO BE MATTE
8. SILKSREEN
 - A. SILKSREEN AS INDICATED WITHIN THE ELECTRONIC DATA USING NON CONDUCTIVE WHITE EPOXY INK
 - B. SILKSREEN TO BE REMOVED FROM VAS, PADS, AND HOLES PROVIDING A MINIMUM CLEARANCE OF 0.005 INCHES
 - C. ANY OTHERS, ULTIMATE OR DESIGNATION SHALL BE NUMBER STAMPED OR SILKSREENED BY THE VENDORS DISCRETION ON OTHER SIDE OF THE BOARD
 - D. OTHER APPLICABLE STANDARDS
 - E. FABRICATE PER IPC-2221, CLASS 2 LEVEL B
 - F. PER IPC-2221, TYPE 3, ASSET 1 & 2, PER A-HOUSE CLASS 2
 - G. FABRICATE IN ACCORDANCE WITH IPC-6012B CLASS 2, PER IPC-6011 USING SUPPLIED DATA FILES
 - H. THE BOARD SHALL CONFORM TO UL94V-0
9. OTHER APPLICABLE NOTES
 - A. REFER TO STACK-UP AND IMPEDANCE INFORMATION
 - B. TEARDROPPING IS ACCEPTABLE ON INNER SIGNAL LAYERS
 - C. CORNER THEVING MAY NOT BE ADDED TO PCB DESIGN, ONLY TO PANEL
 - D. BOW OR TWIST NOT TO EXCEED 0.178 MM (253.3 UAW)
 - E. THE PCB SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS. THE RESULTS OF THIS TEST SHALL BE DOCUMENTED AND DELIVERED WITH EACH LOT
 - F. DIMENSIONAL COMPLIANCE IS REQUIRED
 - G. ALL MATERIALS USED WITHIN THE FABRICATION ARE TO BE ROHS COMPLIANT AND MUST SUPPORT A PB-FREE ASSEMBLY PROCESS (E.G. ACCEPTABLE TIG WELD, ETC)
 - H. PANEL DESIGN: PCBs SHALL BE ROUTED WITH MOUSE BITES, NO V-Score ON ANY SIDE
 - I. INCLUDE TOOLING HOLES AND LOCALS. BOARDS TO REMAIN ON THE PANEL FOR ASSEMBLY.
 - J. TARGET IMPEDANCE LAYER 1: 0.01409 INCH TRACK WIDTH = 50 OHM +/- 10%
 - K. ANY ARTWORK MODIFICATIONS MUST BE REVIEWED AND APPROVED BY MMB NETWORKS PRIOR TO MANUFACTURING